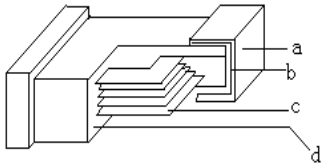
Product Structure



a.Ag layer

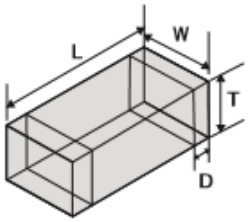
b.Ni/Sn plating

c.Inner electrode

d.Body

Dimension

Part No	L(mm)	W(mm)	T(mm)	D(mm)
160808 (0603)	1.6± 0.20 (0.063± 0.008)	0.8± 0.20 (0.031± 0.008)	0.8± 0.20 (0.031± 0.008)	0.3± 0.2 (0.01± 0.008)
201209 (0805)	2.0± 0.20 (0.079± 0.008)	1.2± 0.20 (0.047± 0.008)	0.9± 0.20 (0.035± 0.008)	0.5± 0.3 (0.020± 0.012)
201609 (0806)	3.2± 0.20 (0.079± 0.008)	1.6± 0.20 (0.063± 0.008)	0.9± 0.20 (0.035± 0.008)	0.5± 0.3 (0.020± 0.012)
252010 (1008)	2.5± 0.20 (0.098± 0.008)	2.0± 0.20 (0.079± 0.008)	1.0± 0.20 (0.039± 0.008)	0.5± 0.3 (0.020± 0.012)



Electrical Characteristics

1608 Type

Part NO	Tolerance	Inductance Hμ	Test frequency(MHz)		SRF(MHZ)min	Ir (mA)Max
CMH160808BR47MT	± 20%	0.047	1	0.10±30%	100	1050
CMH160808BR56MT	± 20%	0.056	1	0.12±30%	100	1050
CMH160808B1R0MT	± 20%	1.0	1	0.20±30%	98	900
CMH160808B1R8MT	± 20%	1.8	1	0.24±30%	95	750
CMH160808B2R2MT	± 20%	2.2	1	0.24±30%	95	750
CMH160808B4R7MT	± 20%	4.7	1	0.50±30%	65	700

2012 Type

Part NO	Tolerance	Inductance Hμ	Test frequency(MHz)		SRF(MHZ)min	Ir (mA)Max
CMH201209A1R0MT	± 20%	1.0	1	0.14±25%	75	300
CMH201209A2R2MT	± 20%	2.2	1	0.224±25%	50	220
CMH201209A3R3MT	± 20%	3.3	1	0.24±25%	35	200
CMH201209A4R7MT	± 20%	4.7	1	0.30±25%	25	180

Part NO	Tolerance	Inductance H	Test frequency(MHz)		SRF(MHZ)min	Ir (mA)Max
CMH201209B1R0MT	± 20%	1.0	1	0.11±25%	75	1150
CMH201209B2R2MT	± 20%	2.2	1	0.20±25%	50	950
CMH201209B3R3MT	± 20%	3.3	1	0.22±25%	35	800
CMH201209B4R7MT	± 20%	4.7	1	0.30±25%	25	750
CMH201209B6R8MT	± 20%	6.8	1	0.30±25%	25	600

2016 Type

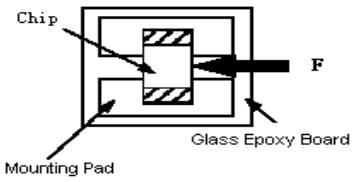
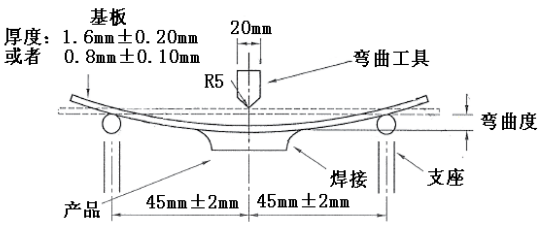
Á Part NO	B%$9* Tolerance	=0&UH Inductance´ Hµ	ÐBNÇ½ Test frequency(MHz)	-₩+kLq	8 BFeNÇ½ SRF(MHZ)min	NÉkw Ir (mA)Max
CMH201609B1R0MT	± 20%	1.0	1	0.10±25%	70	1400
CMH201609B2R2MT	± 20%	2.2	1	0.16±25%	50	1200
CMH201609B3R3MT	± 20%	3.3	1	0.20±25%	40	1200
CMH201609B4R7MT	± 20%	4.7	1	0.26±25%	30	1100

2520 Type

Á Part NO	B%$9* Tolerance	=0&UH Inductance´ Hµ	ÐBNÇ½ Test frequency(MHz)	-₩+kLq	8 BFeNÇ½ SRF(MHZ)min	NÉkw Ir (mA)Max
CMH252010B1R0MT	± 20%	1.0	1	0.06±25%	70	1600
CMH252010B2R2MT	± 20%	2.2	1	0.10±25%	55	1300
CMH252010B3R3MT	± 20%	3.3	1	0.14±25%	30	1200
CMH252010B4R7MT	± 20%	4.7	1	0.18±25%	25	1100

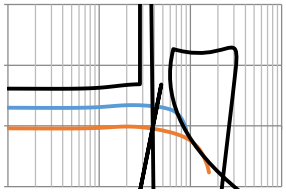
Reliability Test Method

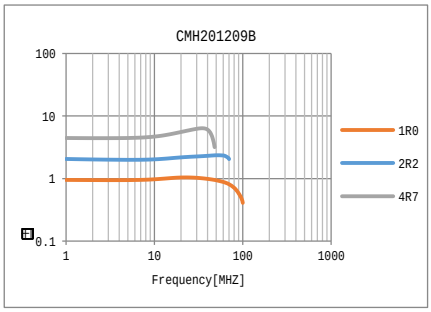
Å No.	N-$ Items	x Requirements	BP₩# Test Methods and Remarks
1	$9* Operating Temperature Range	-	/
	%]@ Solder ability	%ÇÇ +kM˜ 95% 95% or more of electrode area shall be coated by new solder.	N:120 ~ 150 N*: 60s 96.5%Sn/3.0%Ag/0.5%Cu : 245f 5 :10mm W,L* : 5f 1s :3 ~ 5 s Preheating temperature:120˚C to 150˚C Preheating time: 60s Solder 96.5%Sn/3.0%Ag/0.5%Cu of the Sn solder. Solder temperature: 245±5˚C Immersion tin depth:10mm Duration : 5±1s Dip performance to a flux of about:3 ~ 5 s

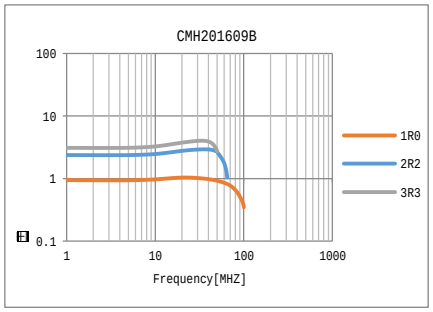
No.	Items	Requirements	Test Methods and Remarks
	Resistance to Soldering Heat	95% (B): 30% (A): 30%At least 95% of terminal electrode should be covered with solder. No mechanical damage. Inductance ： B：change within ±30% A：change within ±30%	: 120 ~150 : 60s 96.5%Sn/3.0%Ag/0.5%Cu : 260 5 :10mm : 10 1s :3 5 s Preheating temperature: 120˚C to 150˚C Preheating time: 60s Solder 96.5%Sn/3.0%Ag/0.5%Cu of the Sn solder. Solder temperature: 260˚C±5˚C Immersion tin depth:10mm Duration : 10±1s Dip performance to a flux of about:3～5 s
	Adhesion of electrode	The termination and body should be no damage.	11608 7N 2012 2016 2520 10N Applied force: 7N force for 1608 series；10N force for 2012、2016、2520 series. Keep time ： 10±1S 
	Low temperature resistance	10% No mechanical damage. Inductance change: within ±10%	:-40 2 : h Temperature:-40±2˚C Testing time: h
	Bending strength	No mechanical damage	: 0.5mm/s, :2mm, 20s 1s Testing board: glass epoxy-resin substrate For 0.5 mm/s compression speed, curvature: 2mm, hold time20s±1s 。 

-NC½]

Inductance Vs. Frequency Characteristics

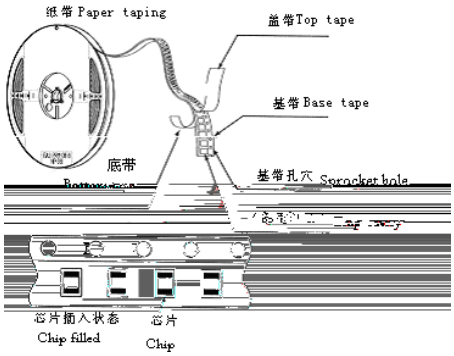




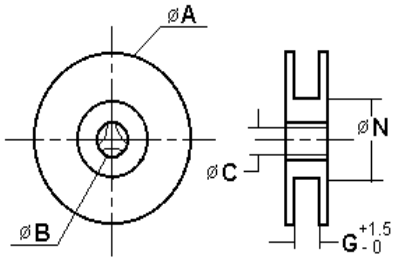


Packaging

* □ Taping drawings

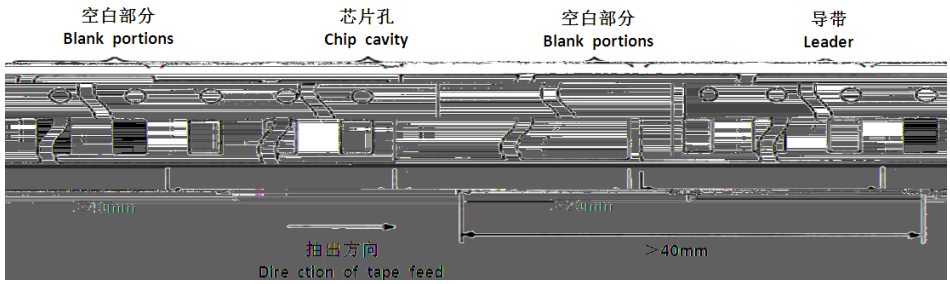


* □ Reel dimensions (Unit: mm)



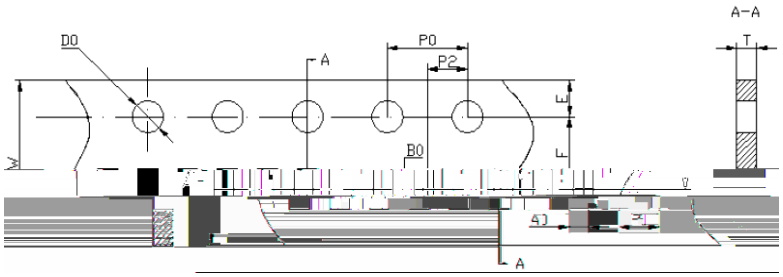
□ Size	A	B	C	N	G
CF-8	178±2.0	22.0±2.0	12.5±1.5	57±2.0	8

* □ Leader and blank portion



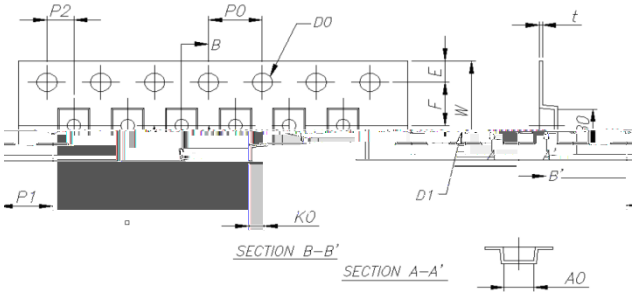
* □ Taping dimensions (Unit: mm)

Paper tape



Part NO.	A0	B0	W	F	E	P1	P2	P0	D0	T
160808	1.10±0.2	1.90±0.2	8.0±0.2	3.5±0.1	1.75±0.2	4.0±0.2	2.0±0.1	4.0±0.2	1.55±0.1	0.95±0.1
201209	1.50±0.2	2.30±0.2	8.0±0.2	3.5±0.1	1.75±0.2	4.0±0.2	2.0±0.1	4.0±0.2	1.55±0.1	0.95±0.1
201609	1.85±0.1	2.35±0.1	8.0±0.1	3.5±0.1	1.75±0.2	4.0±0.2	2.0±0.1	4.0±0.2	1.55±0.1	0.95±0.1

Embossed tape



Á Size	252010
W	8.00+/-0.20
E	1.75+/-0.10
F	3.50+/-0.10
D0	1.50+/-0.10
D1	1.00+/-0.10
P0	4.00+/-0.10
P010	40.0+/-0.20
P1	4.00+/-0.10
P2	2.00+/-0.10
A0	2.20+/-0.10
B0	2.75+/-0.10
K0	1.05+/-0.10
t	0.23+/-0.20

* □ Packaging number (Unit: Pcs)

2± Á SIZE	252010	201609	201209	160808
Ì REEL	3000	4000	4000	4000
"Ì BOX	30000	40000	40000	40000
1Ì CASE	180000	240000	240000	240000